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| Course Title | () | () | Semiconductor Fabrication Processes |
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|----------------------------|-----|--------------------------------------|-------------------|
| () Lecturer | () | / / (Course No. /) | 006147/ /3 |
| (/HP) Contact No. | | / (Class Hour/Venue) | 13:00-15:00 / 109 |
| (Course Prerequisite) | | (Target Student) | 3 |
| E-mail (E-mail Address) | | /Office Hour (Office/Office Hour) | 812 / 15:00-17:00 |

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| (Objectives) | (crystal growth, cleaning, lithography, oxidation, diffusion, ion implantation, thin film deposition, etching, back-end processing) Project Term |
| (Competencies related to this course) | <input type="checkbox"/> (Logical and Critical Thinking) <input checked="" type="checkbox"/> (Creative and Convergent Thinking) <input type="checkbox"/> (Self-management Competency) <input checked="" type="checkbox"/> (Problem Solving Competency) <input type="checkbox"/> (Communication Competency) <input checked="" type="checkbox"/> (Global Competency) <input type="checkbox"/> (Community Competency) |
| CQI (Continuous Quality Improvement Plan) | (3) |
| (Text book) | - Xiao, "Introduction to Semiconductor Manufacturing Technology, 2nd Edition", SPIE (2012) - (2017) |
| (Assignment book) | - Plummer et al., "Silicon VLSI Technology: Fundamentals, Practice, and Modeling", Prentice Hall (2000) - "Silicon Run" VTR tape () - Doering and Nishi(ed), "Handbook of Semiconductor Manufacturing Technology" (2007) |
| (Assignment) | Term project 1: pdf 2: 3: 4: 5: |
| 가 (Course Grading) | [가] (%) : 30, (%) : 40, 가 (%) : 20, (%) : 10, - : 10/23(), : 12/18() 가 F |

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| (Week) | (Course Contents) | (Etc.) | |
|--------|---|--------|--|
| 1 | Introduction and Historical Perspective | | |
| 2 | Modern CMOS Technology | | |
| 3 | CMOS Process Flow | | |
| 4 | Fabrication and Basic Properties of Silicon Wafers | | |
| 5 | Clean Rooms, Wafer Cleaning, and Gettering | | |
| 6 | Lithography | | |
| 7 | Thermal Oxidation and the Si/SiO ₂ Interface | | |
| 8 | | | |

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| (Week) | (Course Contents) | (Etc.) | |
|--------|---------------------------|--------|--|
| 9 | Dopant Diffusion | | |
| 10 | Ion Implantation | | |
| 11 | Thin Film Deposition I | | |
| 12 | Thin Film Deposition II | | |
| 13 | Etching | | |
| 14 | Team Project Presentation | | |
| 15 | Interconnect | | |
| 16 | | | |

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| 가 1 (Additional Guide1) | <p style="text-align: center;">()</p> <p>Students who require special assistance (including special needs students) may contact their professors during the first week of the semester to discuss issues related to attendance, lectures, assignments and exams and request learning assistance.</p> |
| 가 2 (Additional Guide2) | <p style="text-align: center;">가</p> <p>0 - - term paper F ' 0' 0 0 0</p> <p style="text-align: center;">(, ,)</p> |